

## plerow<sup>™</sup> APM0866-P29

#### **High OIP3** Medium Power Amplifier Module

#### **Features**

- · S<sub>21</sub> = 32.2 dB @ 865 MHz
  - = 31.8 dB @ 868 MHz
- · NF of 6.6 dB over Frequency
- · Unconditionally Stable
- · Single 5V Supply
- · High OIP3 @ Low Current

Parameter

**Frequency Range** 

Gain Flatness

Noise Figure

Output IP3 (1)

S11 / S22 (2)

Output P1dB

Switching Time (3)

Supply Current

Supply Voltage

Impedance

Gain

**Specifications (in Production)** 

#### Description

Unit

MHz

dB

dB

dB

dBm

dB

dBm

μsec

mΑ

V

Ω

dBm

mm

The plerow<sup>™</sup> APM-Series is an internally matched amplifier mini-module for such application band in SMD package with the output P1dB of 29 dBm. It is compactly designed for low current consumption and high OIP3. Integrating all the components for biasing and matching within the module enhances production yield and throughput as well. It passes through the stringent DC, RF, and reliability tests. Not sample test but 100% quality control test is made before packing.

Typ. @ T = 25°C,  $V_s$  = 5 V, Freq. = 866.5 MHz,  $Z_{o.sys}$  = 50 ohm

Min

865

31

44

28

Specifications

Тур

32

± 0.2

6.6

47

29

\_

370

5

50

C.W 23 ~ 25 (before fail)

Surface Mount Type, 10Wx10Lx3.8H

Max

868

± 0.3

6.8

-15 / -9

400







1-stage Single Type

#### More Information

Website: www.asb.co.kr E-mail: sales@asb.co.kr

Tel: (82) 42-528-7223 Fax: (82) 42-528-7222

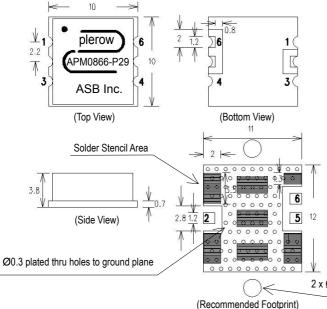
ASB Inc., 4th FI. Venture Town Bldg., 367-17 Goijeong-Dong, Seo-Gu, Daejon 302-716, Korea

Package Type & Size Operating temperature is -40°C to +85°C.

Max. RF Input Power

1) OIP3 is measured with two tones at an output power of 12 dBm / tone separated by 1 MHz.
2) S11/S22 (max) is the worst value within the frequency band.
3) Switching time means the time that takes for output power to get stabilized to its final level after switching DC voltage from 0 V to V<sub>S</sub>.

## Outline Drawing (Unit: mm)



Pin Number	Function	
2	RF In	
5	RF Out	
6	Vs	
Others	Ground	

Note: 1. The number and size of ground via holes in a circuit board is critical for thermal RF grounding considerations.

2. We recommend that the ground via holes be placed on the bottom of all ground pins for better RF and thermal performance, as shown in the drawing at the left side.

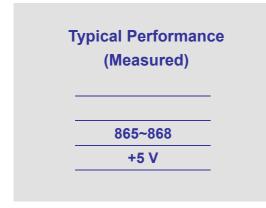
2 x Ø2.0 plated thru holes to screw on heat sinker

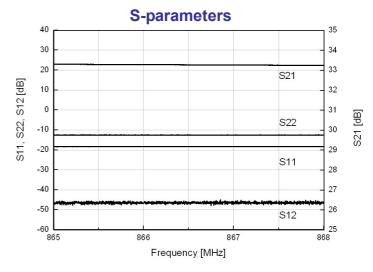
February 2009



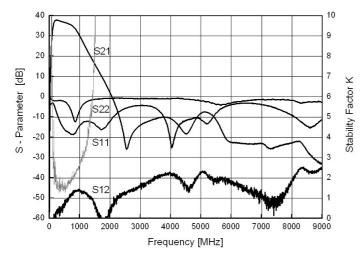
# plerow<sup>™</sup> APM0866-P29

#### High OIP3 Medium Power Amplifier Module

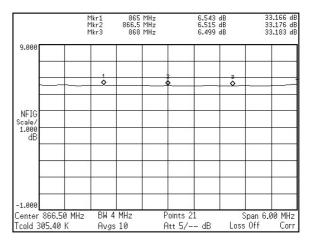




**Stability Factor (K)** 



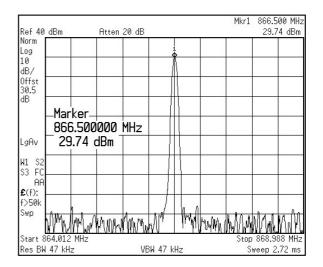




OIP3

Intermod (	Ch Freq 8 TOI)	66.5 MHz	Averages: 2	Trig Free
Center	866.500	0000 MHz		•
Ref 12.5 d #Samp	Bm #Att	en 12 dB		
Log 10 dB/ Offst				
30.5 dB		A	+	
	enter 866.500 MHz Res BW 30 kHz #VBW 3 kHz		Span 5 MHz Sweep 138 ms	
TOI (We	orst Case)		47.19 dBm	
TOI IOM TOI upj		865.0 MHz 868.0 MHz	47.52 dBm 47.19 dBm	

#### P1dB

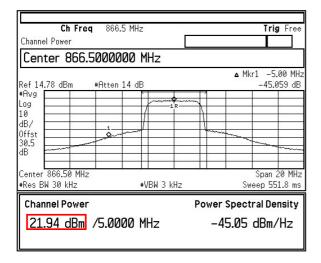


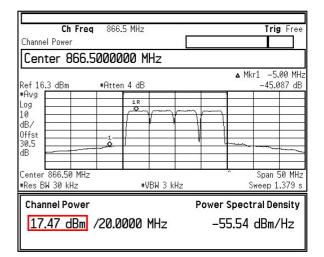


## High OIP3 Medium Power Amplifier Module

#### **Output Channel Power**

(@ ACLR=-45dBc, +/-5MHz Offset)

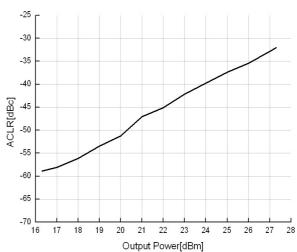




#### **OIP3 vs Output Power**



#### **ACLR vs Channel Power**

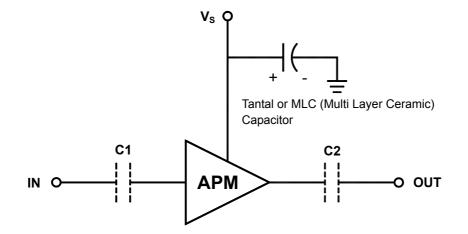


\*\* Test Source : Agilent E4433B (3GPP W-CDMA Test Model-1 64DPCH)



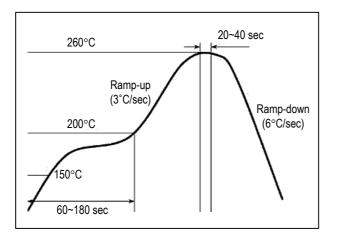
#### High OIP3 Medium Power Amplifier Module

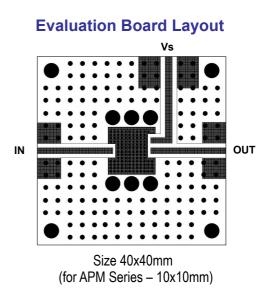
## **Application Circuit**



- The tantal or MLC (Multi Layer Ceramic) capacitor is optional and for bypassing the AC noise introduced from the DC supply. The capacitance value may be determined by customer's DC supply status. The capacitor should be placed as close as possible to V<sub>s</sub> pin and be connected directly to the ground plane for the best electrical performance.
- 2) DC blocking capacitors are always necessarily placed at the input and output port for allowing only the RF signal to pass and blocking the DC component in the signal. The DC blocking capacitors are included inside the APM module. Therefore, C1 & C2 capacitors may not be necessary, but can be added just in case that the customer wants. The value of C1 & C2 is determined by considering the application frequency.

#### **Recommended Soldering Reflow Process**

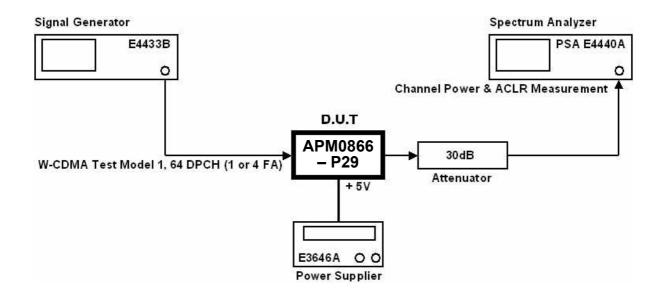




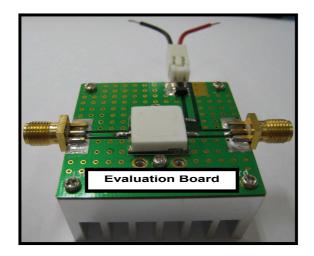


### High OIP3 Medium Power Amplifier Module

## **Channel Power vs. ACLR Test Configuration**



#### **Evaluation Board attached with Heat Sink**



\* In order to prevent damage of D.U.T (APM-Series) from heating, you must to use a properly sized heat sink for testing a module.